











TPS92613-Q1

ZHCSJM3B - APRIL 2019-REVISED JANUARY 2020

TPS92613-Q1 汽车单通道 LED 驱动器

1 特性

- 符合面向汽车 应用的 AEC-Q100 标准:
 - 温度等级 1: -40°C 至 +125°C, T_A
- 提供功能安全
 - 可帮助创建功能安全系统设计的文档
- 宽输入电压范围: 4.5V 至 40V
- 低静态电流和低故障模式电流: 典型值 200µA
- 单路高精度电流调节:
 - 在整个结温范围内精度为 ±4.6%
 - 可通过外部感应电阻器调节的恒定电流
 - 高达 600mA 的最大电流
 - 通过输入 PWM 占空比进行亮度控制
- 与外部电阻器实现热共享
- 低压降电压(包含感应电阻器压降):
 - 最大压降: 10mA 时为 150mV
 - 最大压降: 70mA 时为 400mV
 - 最大压降: 150mA 时为 700mV
 - 最大压降: 300mA 时为 1.3V
- 诊断和保护:
 - 具有自动恢复功能的 LED 开路与短路检测
 - 在低压降运行情况下支持诊断并具有可调阈值
 - 多达 15 个器件的故障总线,可配置为"连带失效"或"仅关闭失效的通道"(N-1)
 - 热关断
- 工作结温范围: -40°C 至 +150°C

2 应用

- 车内照明:顶灯、阅读灯
- 车外照明 小灯:车门把手、盲点检测指示灯、充电口
- 车外照明 后灯:尾灯、中央高位刹车灯、侧标志灯
- 通用 LED 驱动器 应用

3 说明

随着 LED 在汽车 应用中广泛使用,简单的 LED 驱动器越来越受欢迎。与分立式解决方案相比,低成本单片解决方案可降低系统级组件数量,并显著提高电流精度和可靠性。

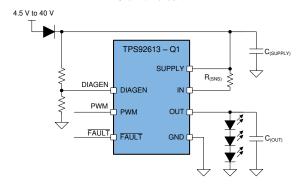
TPS92613-Q1 器件是一款单通道、高侧 LED 驱动器,由汽车电池供电。这是一种简单而巧妙的解决方案,能够为单个 LED 灯串提供恒定电流,并具有全面的 LED 诊断功能。"连带失效"功能可与其他 LED 驱动器(如 TPS9261x-Q1、TPS9263x-Q1 和 TPS92830-Q1 器件)一起工作,从而满足不同的要求。

器件信息(1)

	, , ,	
器件型号	封装	封装尺寸 (标称值)
TPS92613-Q1	TO-263 (7)	10.16mm × 9.85mm

(1) 如需了解所有可用封装,请参阅数据表末尾的可订购产品附录。

典型应用图



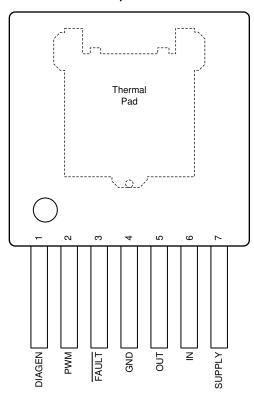


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5 Pin Configuration and Functions

NDR Package 7-Pin TO-263 With Exposed Thermal Pad Top View



Pin Functions

PIN		1/0	DESCRIPTION		
NO.	NAME	I/O	DESCRIPTION		
1	DIAGEN	I	Enable pin for LED open-circuit detection to avoid false open diagnostics during low-dropout operation		
2	PWM	I	PWM input for current output ON/OFF control		
3	FAULT	I/O	Fault output, support one-fails-all-fail fault bus		
4	GND	_	Ground		
5	OUT	0	Constant-current output, connect to anode of the top LED in LED-string		
6	IN	1	Current input		
7	SUPPLY	I	Device supply voltage		
_	Thermal pad	_	Thermal pad, connect to ground		



6 Specifications

6.1 Absolute Maximum Ratings

over operating ambient temperature range (unless otherwise noted) (1)

		MIN	MAX	UNIT
High-voltage input	DIAGEN, IN, PWM, SUPPLY	-0.3	45	V
High-voltage output	OUT	-0.3	45	V
Fault bus	FAULT	-0.3	22	V
IN to OUT	$V_{(IN)} - V_{(OUT)}$	-0.3	45	V
SUPPLY to IN	$V_{(SUPPLY)} - V_{(IN)}$	-0.3	1	V
Operating junction temperature, T _J		-40	150	°C
Storage temperature, T _{stg}	-40	150	°C	

⁽¹⁾ Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under Recommended Operating Conditions. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

6.2 ESD Ratings

.,	Electrostatic discharge Device Charge	Human-body model (HBM), per AEC Q100-002 ⁽¹⁾ Device HBM ESD Classification Level H2	All pins	±2000	.,	
V _(ESD)		Charged-device model (CDM), per AEC Q100-011	All pins	±500	V	
		Device CDM ESD Classification Level C3B	Corner pins (1 and 7)	±750		

⁽¹⁾ AEC Q100-002 indicates that HBM stressing shall be in accordance with the ANSI/ESDA/JEDEC JS-001 specification.

6.3 Recommended Operating Conditions

over operating ambient temperature range (unless otherwise noted)

		MIN	NOM MAX	UNIT
SUPPLY	Device supply voltage	4.5	40	V
IN	Sense voltage	4.4	40	V
PWM	PWM inputs	0	40	V
DIAGEN	Diagnostics enable pin	0	40	V
OUT	Driver output	0	40	V
FAULT	Fault bus	0	7	V
Operating ambient temperature, T _A		-40	125	°C

6.4 Thermal Information

		TPS92613-Q1	
	THERMAL METRIC ⁽¹⁾	NDR (TO-263)	UNIT
		7 PINS	
$R_{\theta JA}$	Junction-to-ambient thermal resistance	28.4	°C/W
$R_{\theta JC(top)}$	Junction-to-case (top) thermal resistance	23.1	°C/W
$R_{\theta JB}$	Junction-to-board thermal resistance	10.1	°C/W
ΨЈТ	Junction-to-top characterization parameter	4.2	°C/W
ΨЈВ	Junction-to-board characterization parameter	9.9	°C/W
R _{0JC(bot)}	Junction-to-case (bottom) thermal resistance	3.5	°C/W

For more information about traditional and new thermal metrics, see the Semiconductor and IC Package Thermal Metrics application report.

6.5 Electrical Characteristics

 $V_{(SUPPLY)} = 5 \text{ V to } 40 \text{ V}, T_J = -40^{\circ}\text{C to } +150^{\circ}\text{C unless otherwise noted}$

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
BIAS						
V _(POR_rising)	Supply voltage POR rising threshold			3.2	4	V



Electrical Characteristics (continued)

 $V_{(SUPPLY)} = 5 \text{ V to } 40 \text{ V}, T_J = -40^{\circ}\text{C to } +150^{\circ}\text{C unless otherwise noted}$

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
$V_{(POR_falling)}$	Supply voltage POR falling threshold		2.2	3		V
I _(Quiescent)	Device standby current	PWM = HIGH	0.1	0.2	0.25	mA
I _(FAULT)	Device current in fault mode	PWM = HIGH, FAULT externally pulled LOW	0.1	0.2	0.25	mA
LOGIC INPUTS (DIAGEN, PWM)					
V _{IL(DIAGEN)}	Input logic-low voltage, DIAGEN		1.045	1.1	1.155	V
V _{IH(DIAGEN)}	Input logic-high voltage, DIAGEN		1.16	1.2	1.24	V
V _{IL(PWM)}	Input logic-low voltage, PWM		1.045	1.1	1.155	V
V _{IH(PWM)}	Input logic-high voltage, PWM		1.16	1.2	1.24	V
CONSTANT-CUR	RENT DRIVER	,				
I _(OUT)	Device output-current range	100% duty cycle	4		600	mA
		T _A = 25°C, V _(SUPPLY) = 4.5 V to 18 V	94	98	102	
$V_{(CS_REG)}$	Sense-resistor regulation voltage	T _A = -40°C to +125°C, V _(SUPPLY) = 4.5 V to 18 V	93.5	98	102.5	mV
R _(CS_REG)	Sense-resistor range	177	0.16		50	Ω
		V _(CS REG) voltage included, current setting of 10 mA		120	150	1
		V _(CS_REG) voltage included, current setting of 70 mA		250	400	1
$V_{(DROPOUT)}$	Voltage dropout from SUPPLY to OUT	V _(CS_REG) voltage included, current setting of 150 mA		430	700	mV
		V _(CS_REG) voltage included, current setting of 300 mA		800	1300	I
DIAGNOSTICS		,				
V _(OPEN_th_rising)	LED open rising threshold, V _(IN) – V _(OUT)		235	290	335	mV
V _(OPEN_th_falling)	LED open falling threshold, V _(IN) – V _(OUT)		70	100	135	mV
V _(SG_th_rising)	Channel output V _(OUT) short-to-ground rising threshold		1.14	1.2	1.26	٧
V _(SG_th_falling)	Channel output V _(OUT) short-to-ground falling threshold		0.82	0.865	0.91	٧
I _(Retry)	Channel output V _(OUT) short-to-ground retry current		0.64	1.08	1.528	mA
FAULT						
V _{IL(FAULT)}	Logic input low threshold				0.7	V
V _{IH(FAULT)}	Logic input high threshold		2			٧
V _{OL(FAULT)}	Logic output low threshold	With 500-µA external pullup			0.4	V
V _{OH(FAULT)}	Logic output high threshold	With 1-µA external pulldown, V _(SUPPLY) = 12 V	5		7	٧
I _(FAULT_pulldown)	FAULT internal pulldown current		500	750	1000	μΑ
I _(FAULT_pullup)	FAULT internal pullup current		5	8	12	μΑ
THERMAL PROT	ECTION					
T _(TSD)	Thermal shutdown junction temperature threshold		157	172	187	°C
T _(TSD_HYS)	Thermal shutdown junction temperature hysteresis			15		°C

6.6 Timing Requirements

		MIN	NOM	MAX	UNIT
t _(PWM_delay_rising)	PWM rising edge delay, 50% PWM voltage to 10% of output current closed loop, t2 - t1 as shown in Figure 1	10	17	25	μs
t(PWM_delay_falling)	PWM falling edge delay, 50% PWM voltage to 90% of output current open loop, t5 - t4 as shown in Figure 1	15	21	30	μs
t(DEVICE_STARTUP)	SUPPLY rising edge to 10% output current at 200-mA set current and 14 V, t8 - t7 as shown in Figure 1		100	150	μs
t _(OPEN_deg)	LED-open fault-deglitch time	80	125	175	μs
t _(SG_deg)	Output short-to-ground detection deglitch time	80	125	175	μs
t _(TSD_deg)	Thermal over temperature deglitch timer		50		μs
t _(Recover_deg)	Fault recovery deglitch timer	8.5	16	25	μs



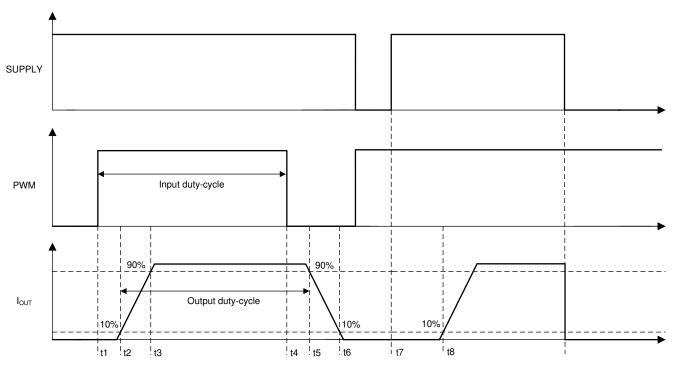
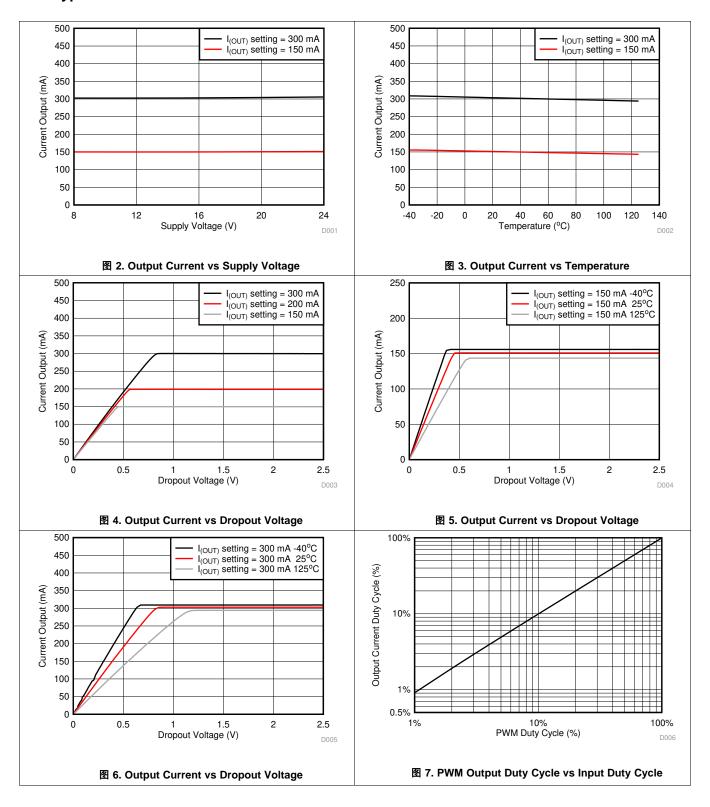


图 1. Output Timing Diagram

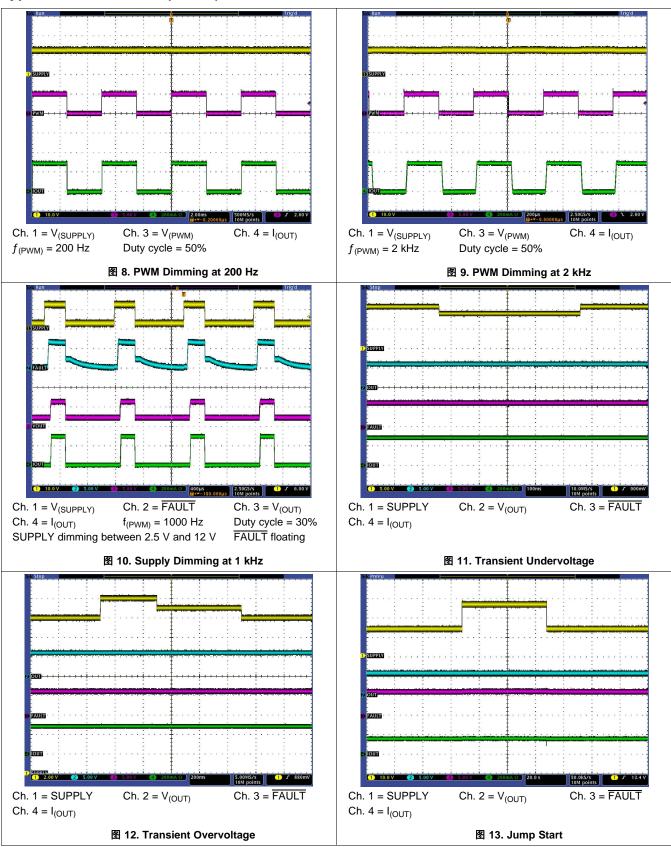


6.7 Typical Characteristics



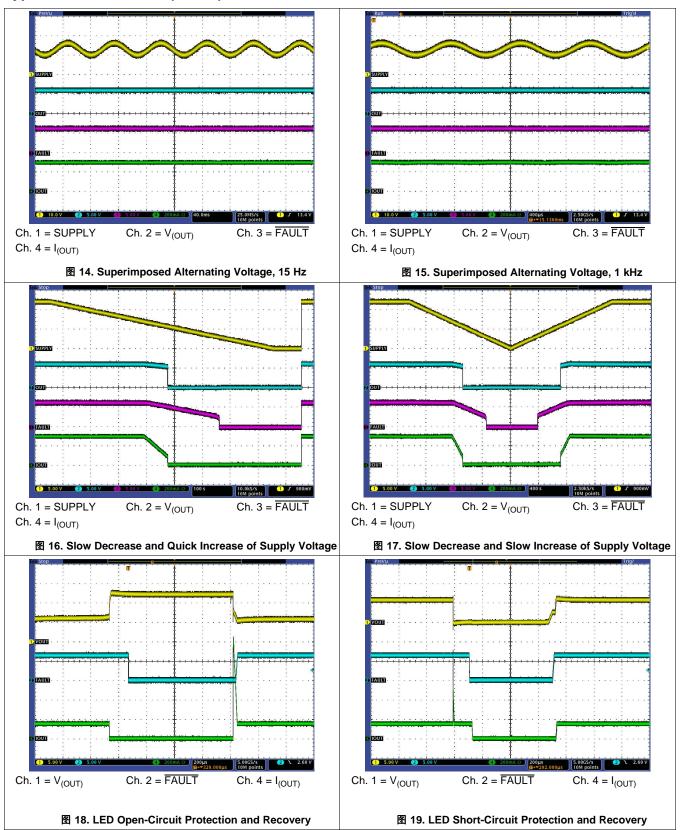


Typical Characteristics (接下页)





Typical Characteristics (接下页)





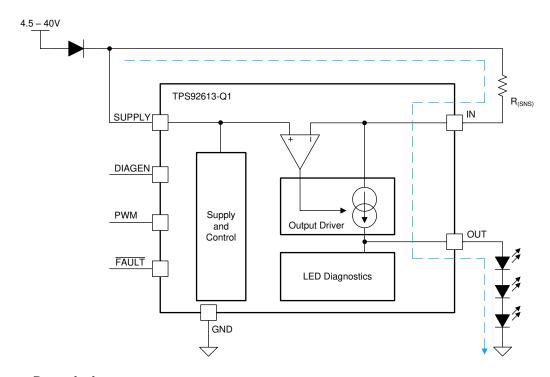
7 Detailed Description

7.1 Overview

The TPS92613-Q1 is one device of single-channel linear LED driver family including TPS92610-Q1, TPS92611-Q1 and TPS92612-Q1. The family provides a simple solution for automotive LED applications. Different package options in the family provide variable current ranges and diagnostic options. The TPS92613-Q1 device in a TO-263 package supports both LED open-circuit detection and short-to-ground detection. The TPS92613-Q1 can be used with other TPS9261x-Q1, TPS9263x-Q1 and TPS92830-Q1 family devices together to realize one-fails-all-fail protection by tying all FAULT pins together as a fault bus.

The current output at OUT pin can be set by an external $R_{(SNS)}$ resistor. Current flows from the supply through the $R_{(SNS)}$ resistor into the integrated current regulation circuit and to the LEDs through OUT pin.

7.2 Functional Block Diagram



7.3 Feature Description

7.3.1 Power Supply

7.3.1.1 Power-On Reset (POR)

The TPS92613-Q1 device has an internal power-on-reset (POR) function. When power is applied to the SUPPLY pin, the internal POR circuit holds the device in reset state until $V_{(SUPPLY)}$ is above $V_{(POR_rising)}$.

7.3.1.2 Low-Quiescent-Current

The TPS92613-Q1 device consumes minimal quiescent current, less than 250 µA into SUPPLY when the FAULT pin is externally pulled LOW. At the same time, the device shuts down the output driver.

If device detects an internal fault, it pulls down the FAULT pin by an internal typical 750-µA constant current as a fault indication to the fault bus.



7.3.2 Constant-Current Driver

The TPS92613-Q1 device is a high-side current driver for driving LEDs. The device controls the output current through regulating the voltage drop on an external high-side current-sense resistor, $R_{(SNS)}$. An integrated error amplifier drives an internal power transistor to maintain the voltage drop on the current-sense resistor $R_{(SNS)}$ to $V_{(CS_REG)}$ and therefore regulates the current output to target value. When the output current is in regulation, the current value can be calculated by using $\Delta \vec{x}$ 1.

$$I_{(OUT)} = \frac{V_{(CS_REG)}}{R_{(SNS)}}$$

where

•
$$V_{(CS, REG)} = 98 \text{ mV (typical)}$$
 (1)

When the supply voltage drops below total LED string forward voltage plus required dropout voltage, $V_{(DROPOUT)}$, the TPS92613-Q1 is not able to deliver enough current output as set by the value of $R_{(SNS)}$, and the voltage across the current-sense resistor $R_{(SNS)}$ is less than $V_{(CS\ REG)}$.

7.3.3 PWM Control

The pulse width modulation (PWM) input of the TPS92613-Q1 functions as enable for the output current. When the voltage applied on the PWM pin is higher than $V_{IH(PWM)}$, the output current is enabled. When the voltage applied on PWM pin is lower than $V_{IL(PWM)}$, the output current is disabled as well as the diagnostic features. Besides output current enable and disable function, the PWM input of TPS92613-Q1 also supports adjustment of the average current output for brightness control if the frequency of applied PWM signal is higher than 100 Hz, which is out of visible frequency range of human eyes. TI recommends a 200-Hz PWM signal with 1% to 100% duty cycle input for brightness control. See to 20 for typical PWM dimming application.

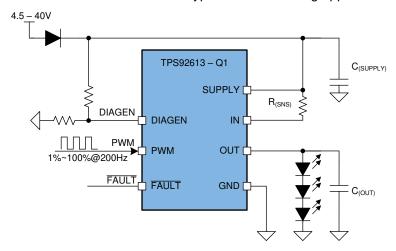


图 20. Typical Application Schematic for PWM Dimming

7.3.4 Supply Control

The TPS92613-Q1 supports supply control to turn ON and OFF output current. When the voltage applied on the SUPPLY pin is higher than the LED string forward voltage plus needed $V_{(DROPOUT)}$ at required current, and the PWM pin voltage is high, the output current is turned ON and well regulated. However, if the voltage applied on the SUPPLY pin is lower than $V_{(POR_falling)}$, the output current is turned OFF. With this feature, the power-supply voltage in the designed pattern controls the output current ON/OFF. The brightness can be adjustable if the ON/OFF frequency is fast enough. Because of the high accuracy design of PWM threshold in TPS92613-Q1, TI recommends a resistor divider on the PWM pin to set the SUPPLY threshold higher than LED forward voltage plus $V_{(DROPOUT)}$ as shown in 21. When the voltage on the PWM pin is higher than $V_{IH(PWM)}$, the output current is turned OFF.



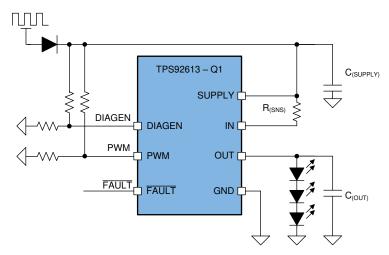


图 21. Typical Application Schematic for SUPPLY Control

7.3.5 Diagnostics and Protection

The TPS92613-Q1 device provides advanced diagnostics and fault-protection features for automotive exterior lighting systems. The device is able to detect and protect fault from LED-string short-to-GND, LED-string open-circuit and junction overtemperature scenarios. It also supports a one-fails—all-fail fault bus design that can flexibly fit different regulatory requirements.

7.3.5.1 Open-Circuit Detection

The TPS92613-Q1 device has LED open-circuit detection. The LED open-circuit detection monitors the output voltage when the current output is enabled. The LED open-circuit detection is only enabled when DIAGEN is HIGH. A short-to-battery fault is also detected and recognized as an LED open-circuit fault.

The TPS92613-Q1 monitors dropout-voltage differences between the IN and OUT pins when PWM is HIGH. The voltage difference $V_{(IN)} - V_{(OUT)}$ is compared with the internal reference voltage $V_{(OPEN_th_falling)}$ to detect an LED open-circuit incident. If $V_{(IN)} - V_{(OUT)}$ falls below the $V_{(OPEN_th_falling)}$ voltage longer than the deglitch time of $t_{(OPEN_deg)}$, the device asserts an open-circuit fault. Once an LED open-circuit failure is detected, the internal constant-current sink pulls down the FAULT pin voltage. During the deglitch time period, if $V_{(IN)} - V_{(OUT)}$ rises above $V_{(OPEN_th_rising)}$, the deglitch timer is reset.

The TPS92613-Q1 keeps the current output enabled to retry after LED open-circuit fault is detected if the PWM input is HIGH; the device sources a small current I_(retry) from IN to OUT when PWM input is LOW. In either scenario, once the fault condition is removed, the device resumes normal operation and releases the FAULT pin.

7.3.5.2 Short-to-GND Detection

The TPS92613-Q1 device has LED short-to-GND detection. The LED short-to-GND detection monitors the output voltage when the output current is enabled. Once a short-to-GND LED failure is detected, the device turns off the output channel and retries automatically, regardless of the state of the PWM input. If the retry mechanism detects the removal of the LED short-to-GND fault, the device resumes to normal operation.

The TPS92613-Q1 monitors the $V_{(OUT)}$ voltage and compares it with the internal reference voltage to detect a short-to-GND failure. If $V_{(OUT)}$ falls below $V_{(SG_th_falling)}$ longer than the deglitch time of $t_{(SG_deg)}$, the device asserts the short-to-GND fault and pulls low the FAULT pin. During the deglitching time period, if $V_{(OUT)}$ rises above $V_{(SG_th_fsing)}$, the timer is reset.

Once the TPS92613-Q1 has asserted a short-to-GND fault, the device turns off the output channel and retries automatically with a small current. During retrying the device sources a small current $I_{(retry)}$ from IN to OUT to pull up the LED loads continuously. Once auto-retry detects output voltage rising above $V_{(SG_th_falling)}$, it clears the short-to-GND fault and resumes to normal operation.



7.3.5.3 Overtemperature Protection

The TPS92613-Q1 device monitors device junction temperature. When the junction temperature reaches thermal shutdown threshold $T_{(TSD)}$, the output shuts down. Once the junction temperature falls below $T_{(TSD)} - T_{(TSD_HYS)}$, the device recovers to normal operation. During overtemperature protection, the FAULT pin is pulled low.

7.3.5.4 DIAGEN

The TPS92613-Q1 device supports the DIAGEN pin with an accurate threshold to disable the LED open-circuit diagnostic functions. The DIAGEN pin can be used to enable or disable LED open-circuit protection based on SUPPLY pin voltage sensed by an external resistor divider. When the voltage applied on DIAGEN pin is higher than the threshold $V_{\text{IH}(\text{DIAGEN})}$, the device enables LED open-circuit diagnosis. When $V_{\text{(DIAGEN)}}$ is lower than the threshold $V_{\text{IL}(\text{DIAGEN})}$, the device disables LED-open-circuit detection.

Only LED open-circuit detection can be disabled by pulling down the DIAGEN pin. The LED short-to-GND detection and overtemperature protection cannot be turned off by pulling down the DIAGEN pin.

7.3.5.5 Low-Dropout Operation

When the supply voltage drops below LED string total forward voltage plus $V_{(DROPOUT)}$ at required current, the TPS92613-Q1 device operates in low-dropout conditions to deliver current output as close as possible to target value. The actual current output is less than preset value due to insufficient headroom voltage for power transistor. As a result, the voltage across the sense resistor fails to reach the regulation target.

If the TPS92613-Q1 is designed to operate in low-dropout condition, and the open-circuit diagnostics must be disabled by pulling the DIAGEN pin voltage lower than $V_{\text{IL}(\text{DIAGEN})}$. Otherwise, the TPS92613-Q1 detects an open-circuit fault and reports a fault indication on the FAULT pin. The DIAGEN pin is used to avoid false diagnostics due to low supply voltage.

In low-dropout operation, a diode in parallel with the sense resistor is recommended to clamp the voltage between SUPPLY and IN (across the sense resistor) in case of a large current pulse during recovery.

7.3.6 FAULT Bus Output With One-Fails-All-Fail

During normal operation, The $\overline{\text{FAULT}}$ pin of TPS92613-Q1 is weakly pulled up by an internal pullup current source, $I_{(\text{FAULT}_\text{pullup})}$ higher than $V_{\text{OH}(\text{FAULT})}$. If any fault scenario occurs, the $\overline{\text{FAULT}}$ pin is strongly pulled low by the internal pulldown current sink, $I_{(\text{FAULT}_\text{pulldown})}$ to report out the fault alarm.

Meanwhile, the TPS92613-Q1 also monitors the \overline{FAULT} pin voltage internally. If the \overline{FAULT} pin of the TPS92613-Q1 is pulled low by external current sink below $V_{IL(FAULT)}$, the current output is turned off even though there is no fault detected on owned output. The device does not resume to normal operation until the \overline{FAULT} pin voltage rises above $V_{IH(FAULT)}$.

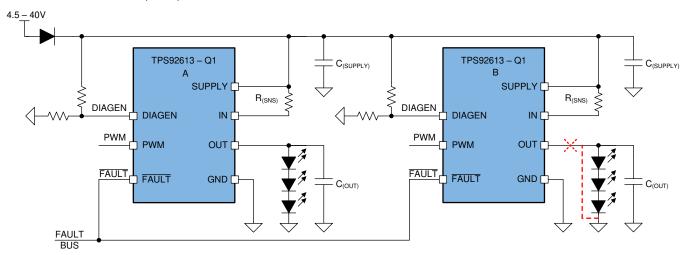


图 22. Typical Application Schematic for One-Fails-All-Fail



Based on this feature, the TPS92613-Q1 device is able to construct a FAULT bus by tying FAULT pins from multiple TPS9261x-Q1, TPS9263x-Q1 or TPS92830-Q1 devices to realize one-fails-all-fail function as 22 showing. The right side TPS92613-Q1 (B) detects either LED open-circuit fault or LED short-to-GND fault and pulls low the FAULT pin. The low voltage on FAULT pin is detected by left side TPS92613-Q1 (A) because the FAULT pins are connected of two devices. The left TPS92613-Q1 (A) turns off the output current as a result.

If the FAULT pin is externally pulled up with a current larger than I_(FAULT_pulldown), the one-fails–all-fail function is disabled and only the faulty channel is turned off.

The FAULT bus is able to support up to 15 pieces of TPS9261x-Q1, TPS9263x-Q1, or TPS92830-Q1 devices.

7.3.7 Fault Table

表 1. Fault Table With DIAGEN = HIGH

FAULT BUS STATUS	FAULT TYPE	DETECTION MECHANISM	CURRENT OUTPUT	DEGLITCH TIME	FAULT BUS	FAULT HANDLING ROUTINE	FAULT RECOVERY
FAULT floating	Open-circuit or short-to-supply	$V_{(IN)} - V_{(OUT)} < V_{(OPEN_th_falling)}$	On	t _(OPEN_deg)	Constant- current pulldown	Device works normally with FAULT pin pulled low. Device sources I _(retry) current when PWM is LOW. Device keeps output normal when PWM is HIGH.	Auto recovery
or externally pulled up	Short-to-ground	V _(OUT) < V _(SG_th_falling)	On	t _(SG_deg)	Constant- current pulldown	Device turns output off and retries with constant current I _(retry) , ignoring the PWM input.	Auto recovery
	Overtemperature	$T_J > T_{(TSD)}$	On or off	t _(TSD_deg)	Constant- current pulldown	Device turns output off.	Auto recovery
Externally pulled low	Device turns output off						

表 2. Fault Table With DIAGEN = LOW

FAULT BUS STATUS	FAULT TYPE	DETECTION MECHANISM	CURRENT OUTPUT	DEGLITCH TIME	FAULT BUS	FAULT HANDLING ROUTINE	FAULT RECOVERY
	Open-circuit or short-to-supply				Ignored		
FAULT floating or externally pulled up	Short-to-ground	V _{OUT} < V(SG_th_falling)	On	t(SG_deg)	Constant- current pulldown	Device turns output off and retries with constant current I _(retry) , ignoring the PWM input.	Auto recovery
	Overtemperature	$T_J > T_{(TSD)}$	On or off	t _(TSD_deg)	Constant- current pulldown	Device turns output off.	Auto recovery
Externally Device turns output off pulled low							



7.4 Device Functional Modes

7.4.1 Undervoltage Lockout, V_(SUPPLY) < V_(POR_rising)

When the device is in undervoltage lockout status, the TPS92613-Q1 device disables all functions until the supply rises above the $V_{(POR_rising)}$ threshold.

7.4.2 Normal Operation V_(SUPPLY) ≥ 4.5 V

The device drives an LED string in normal operation. With enough voltage drop across SUPPLY and OUT, the device is able to drive the output in constant-current mode.

7.4.3 Low-Voltage Dropout Operation

When the device drives an LED string in low-dropout operation, if the voltage drop is less than the open-circuit detection threshold, the device may report a false open-circuit fault. TI recommends only enabling the open-circuit detection when SUPPLY voltage is enough higher than LED string voltage to avoid a false open-circuit detection.

7.4.4 Fault Mode

When the device detects an open circuit or a shorted LED, the device tries to pull down the $\overline{\text{FAULT}}$ pin with a constant current. If the FAULT bus is pulled down, the device switches to fault mode and consumes a fault current of $I_{\text{(FAULT)}}$.



8 Application and Implementation

注

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

8.1 Application Information

In automotive lighting applications, thermal performance and LED diagnostics are always design challenges for linear LED drivers.

The TPS92613-Q1 device is capable of detecting LED open-circuit and LED short-circuits. To increase current-driving capability, the TPS92613-Q1 device supports using an external parallel resistor to help dissipate heat as following section *Single-Channel LED Driver With Heat Sharing* describes. This method provides a low-cost solution of using external resistors to minimize thermal accumulation on the device itself due to large voltage difference between input voltage and LED string forward voltage, while still keeping high accuracy of the total current output. Note that the one-fails—all-fail feature is not supported by this topology.

8.2 Typical Applications

8.2.1 Single-Channel LED Driver With Diagnostics

The TPS92613-Q1 is an easy-to-use solution for LED driver applications with diagnostics requirements.

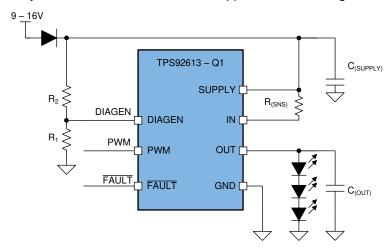


图 23. Typical Application Diagram

8.2.1.1 Design Requirements

Input voltage range is from 9 V to 16 V, LED maximum forward voltage $V_{F_MAX} = 2.5$ V, minimum forward voltage $V_{F_MIN} = 1.9$ V, current $I_{(LED)} = 250$ mA. PWM input is adopted for LED brightness adjust and LED ON/OFF control.

8.2.1.2 Detailed Design Procedure

STEP 1: Determine the current setting resistor, R_(SNS) value by using 公式 2.

$$R_{(SNS)} = \frac{V_{(CS_REG)}}{I_{(LED)}} = 0.392\Omega$$

where

• V_(CS_REG) = 98 mV (typical.)

(2)



STEP 2: Design the threshold voltage for SUPPLY to enable the LED open-circuit diagnostics and calculate the resistor divider value.

LED-string maximum forward voltage = 3 x 2.5 V = 7.5 V. To avoid the open-circuit fault reported in low-dropout operation conditions, additional headroom between SUPPLY and OUT needs to be considered. The TPS92613-Q1 device must disable open-circuit detection when the supply voltage is below LED-string maximum forward voltage plus maximum $V_{(OPEN\ th\ rising)}$ and maximum $V_{(CS\ REG)}$. The voltage divider resistor, R_1 and R_2 value can be calculated by 公式 3.

$$V_{IL(DIAGEN)} = \frac{\left(V_{\left(OPEN_th_rising\right)} + V_{\left(CS_REG\right)} + V_{\left(OUT\right)}\right) \times R_{1}}{R_{1} + R_{2}}$$

where

- V_{IL(DIAGEN)} = 1.045 V (minimum)
- $V_{(OPEN_th_rising)} = 335 \text{ mV (maximum)}$
- V_(CS_REG) = 102.5 mV (maximum)

•
$$R_1 = 10 \text{ k}\Omega \text{ recommended}$$
 (3)

The calculated result for R_2 is 65.7 k Ω when $V_{(OUT)}$ maximum voltage is 7.5 V.

STEP 3: Thermal analysis for the worst application conditions.

Normally the thermal analysis is necessary for linear LED-driver applications to ensure that the operation junction temperature of TPS92613-Q1 is well managed. The total power consumption on the TPS92613-Q1 itself is one important factor determining operation junction temperature, and it can be calculated by using 公式 4. Based on the worst-case analysis for maximum power consumption on device, consider either optimizing PCB layout for better power dissipation as Layout describes or adding an extra heat-sharing resistor as described in Single-Channel LED Driver With Heat Sharing.

$$\begin{split} P_{\text{(DEV)}} &= \left(V_{\text{(SUPPLY)}} - V_{\text{(CS_REG)}} - V_{\text{(OUT)}} \right) \times I_{\text{(LED)}} + V_{\text{(SUPPLY)}} \times I_{\text{(Quiescent)}} \\ P_{\text{(DEV_MAX)}} &= \left(16 - 3 \times 1.9 - 0.098 \right) \times 0.25 + 16 \times 0.00025 = 2.55 W \end{split}$$

where

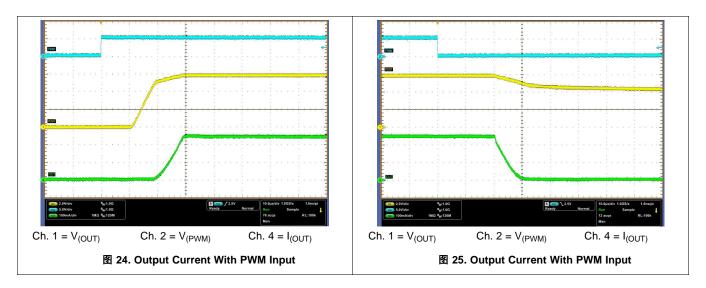
•
$$V_{(CS, REG)} = 98 \text{ mV (typical)}$$

In this application, the calculated result for maximum power consumption on the TPS92613-Q1 is 2.55 W at $V_{(SUPPLY)} = 16 \text{ V}$ and $I_{(LED)} = 250 \text{ mA conditions}$.

TI recommends to add capacitors C_(SUPPLY) at SUPPLY and C_(OUT)at OUT. TI recommends one 1-μF capacitor plus one 100-nF decoupling ceramic capacitor close to the SUPPLY pin for C_(SUPPLY) and a 10-nF ceramic capacitor close to the OUT pin for $C_{(OUT)}$. The larger capacitor for $C_{(SUPPLY)}$ or $C_{(OUT)}$ is helpful for EMI and ESD immunity; however, large C_(OUT) takes a longer time to charge up the capacitor and may affect PWM dimming performance.



8.2.1.3 Application Curves



8.2.2 Single-Channel LED Driver With Heat Sharing

Using parallel resistors, thermal performance can be improved by balancing current between the TPS92613-Q1 device and the external resistors as follows. As the current-sense resistor controls the total LED string current, the LED string current $I_{(LED)}$ is set by $V_{(CS_REG)} / R_{(SNS)}$, while the TPS92613-Q1 current $I_{(DRIVE)}$ and parallel resistor current $I_{(P)}$ combine to the total current.

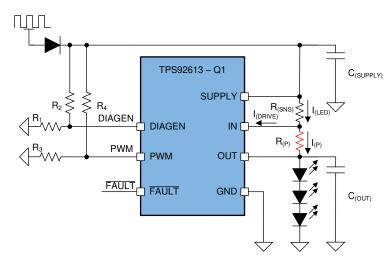


图 26. Supply Control With Heat Sharing Resistor

8.2.2.1 Design Requirements

Input voltage range is 9 V to 16 V, LED maximum forward voltage V_{F_MAX} = 2.5 V, minimum forward voltage V_{F_MIN} = 1.9 V, current $I_{(LED)}$ = 500 mA. And supply control is adopted for LED brightness adjust and LED ON/OFF control. The high level of $V_{(SUPPLY)}$ is 9 V to 16 V, and the low level of $V_{(SUPPLY)}$ is between 0 V to 3 V.



8.2.2.2 Detailed Design Procedure

Note that the parallel resistor path cannot be shut down by PWM or fault protection. If PWM control is required, TI recommends an application circuit as described in

■ 27.

In linear LED driver applications, the large input voltage variation generates the most of the thermal concerns. The resistor current, as indicated by Ohm's law, depends on the voltage across the external resistors. The TPS92613-Q1 controls the driver current I_(DRIVE) to attain the desired total current. If I_(P) increases, the TPS92613-Q1 device decreases I_(DRIVE) to compensate, and vice versa.

While in low-dropout operation, the voltage across the R_(P) resistor may be close to zero, so that almost no current can flow through the external resistor R_(P).

When the input voltage is high, the parallel-resistor current $I_{(P)}$ is proportional to the voltage across the parallel resistor R_(P). The parallel resistor R_(P) takes the majority of the total string current, generating maximum heat.

In this case, the parallel resistor value must be carefully calculated to ensure that 1) enough output current is achieved in low-dropout operation, 2) thermal dissipation for both the TPS92613-Q1 device and the resistor is within their thermal dissipation limits, and 3) device current in the high-voltage mode is above the minimal outputcurrent requirement.

STEP 1: Determine the current setting resistor, $R_{(SNS)}$ value by using 公式 5.

$$R_{(SNS)} = \frac{V_{(CS_REG)}}{I_{(LED)}} = 0.196\Omega$$

where

•
$$V_{(CS_REG)} = 98 \text{ mV (typical)}$$

•
$$I_{(LED)} = 500 \text{ mA}$$
 (5)

The calculated result for $R_{(SNS)}$ is 0.196 Ω .

STEP 2: Calculate the parallel resistor, $R_{(P)}$ value by using 公式 6.

The parallel resistor R_(P) is recommended to consume 50% of the total current at maximum supply voltage.

$$R_{(P)} = \frac{V_{(SUPPLY)} - V_{(CS_REG)} - V_{(OUT)}}{0.5 \times I_{(LED)}} = \frac{16 - 0.098 - 3 \times 1.9}{0.5 \times 0.5} \approx 40\Omega$$

where

•
$$V_{(CS, REG)} = 98 \text{ mV (typical)}$$

The calculated result for $R_{(P)}$ is about 40 Ω at $V_{(SUPPLY)} = 16 \text{ V}$.

STEP 3: Design the threshold voltage for SUPPLY to enable the LED open-circuit diagnostics and calculate voltage divider resistor value for R₁ and R₂.

LED-string maximum forward voltage = 3 x 2.5 V = 7.5 V. To avoid the open-circuit fault reported in low-dropout operation conditions, additional headroom between SUPPLY and OUT needs to be considered. The TPS92613-Q1 device must disable open-circuit detection when the supply voltage is below LED-string maximum forward voltage plus maximum V_(OPEN_th_rising) and maximum V_(CS_REG). The voltage divider resistor, R₁ and R₂ value can be calculated by 公式 7.

$$V_{IL(DIAGEN)} = \frac{\left(V_{\left(OPEN_th_rising\right)} + V_{\left(CS_REG\right)} + V_{\left(OUT\right)}\right) \times R_{1}}{R_{1} + R_{2}}$$

where

- $V_{IL(DIAGEN)} = 1.045 \text{ V (minimum)}$
- V_(OPEN_th_rising) = 335 mV (maximum)
- V_(CS REG) = 102.5 mV (maximum)
- $R_1 = 10 \text{ k}\Omega \text{ recommended}$ (7)



The calculated result for R_2 is 65.7 k Ω when $V_{(OUT)}$ maximum voltage is 7.5 V.

STEP 4: Design the threshold voltage for PWM to enable current output and calculate voltage divider resistor value for R₃ and R₄.

Because the supply control is adopted for the LED ON/OFF and brightness control, a pulse square voltage with power capability is applied on the SUPPLY pin to enable and disable current output to OUT. In order to ensure the current output of TPS92613-Q1 is fully enabled when applied voltage on SUPPLY pin is high enough and the current output is truly shutdown when the applied voltage goes low. A voltage divider from supply to control PWM needs to be designed to setup a threshold of supply voltage. The resistor R_3 and R_4 of voltage divider can be calculated by $\Delta \vec{\pi}$ 8.

$$V_{\text{IL(PWM)}} = \frac{V_{\text{(SUPPLY)}} \times R_3}{R_3 + R_4}$$

where

•
$$R_3 = 10 \text{ k}\Omega \text{ recommended}$$
 (8)

The calculated result for R_4 is 30.5 k Ω if LED must be turned on when $V_{(SUPPLY)}$ voltage is higher than 5 V.

STEP 5: Thermal analysis for the worst application conditions.

The total device power consumption can be calculated by 公式 9.

$$\begin{split} P_{\left(\text{DEV}\right)} = & \left(V_{\left(\text{SUPPLY}\right)} - V_{\left(\text{CS_REG}\right)} - V_{\left(\text{OUT}\right)}\right) \times \left(I_{\left(\text{LED}\right)} - \frac{V_{\left(\text{SUPPLY}\right)} - V_{\left(\text{CS_REG}\right)} - V_{\left(\text{OUT}\right)}}{R_{\left(P\right)}}\right) + V_{\left(\text{SUPPLY}\right)} \times I_{\left(\text{Quiescent}\right)} \\ P_{\left(\text{DEV_MAX}\right)} = & \left(16 - 0.098 - 3 \times 1.9\right) \times \left(0.5 - \frac{16 - 0.098 - 3 \times 1.9}{40}\right) + 16 \times 0.00025 = 2.50 \text{W} \end{split}$$

where

•
$$V_{(CS_REG)} = 98 \text{ mV (typical)}$$

•
$$I_{\text{(Quiescent)}} = 250 \,\mu\text{A} \,(\text{maximum})$$
 (9)

The calculated maximum power consumption on the TPS61193-Q1 is 2.5 W at $V_{(SUPPLY)} = 16 \text{ V}$, $V_{(OUT)} = 3 \times 1.9 \text{ V} = 5.7 \text{ V}$ and $I_{(LED)} = 500 \text{ mA}$.

The power consumption on resistor $R_{(P)}$ can be calculated through $\Delta \stackrel{\cdot}{\lesssim} 10$.

$$P_{(RP)} = \frac{\left(V_{(SUPPLY)} - V_{(CS_REG)} - V_{(OUT)}\right)^2}{R_{(P)}}$$

$$P_{(RP_MAX)} = \frac{(16-3\times1.9-0.098)^2}{40} = 2.6W$$

where

•
$$V_{(CS_REG)} = 98 \text{ mV (Typ.)}$$
 (10)

The calculated maximum power consumption on the 40 Ω , $R_{(P)}$ parallel resistor is 2.6 W at $V_{(SUPPLY)}$ = 16 V and $V_{(OUT)}$ = 3 x 1.9 V = 5.7 V.

TI recommends adding capacitors $C_{(SUPPLY)}$ at SUPPLY and $C_{(OUT)}$ at OUT. One 1- μ F capacitor plus one 100-nF decoupling ceramic capacitor close to the SUPPLY pin is recommended for $C_{(SUPPLY)}$, and a 10-nF ceramic capacitor close to the OUT pin is recommended for $C_{(OUT)}$. The larger capacitor for $C_{(SUPPLY)}$ or $C_{(OUT)}$ is helpful for EMI and ESD immunity, however large $C_{(OUT)}$ takes a longer time to charge up the capacitor and could affect PWM dimming performance.



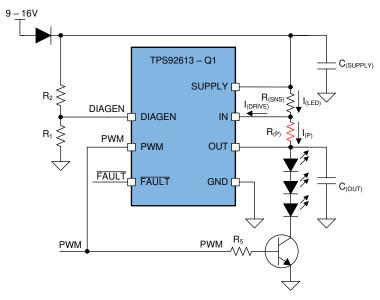
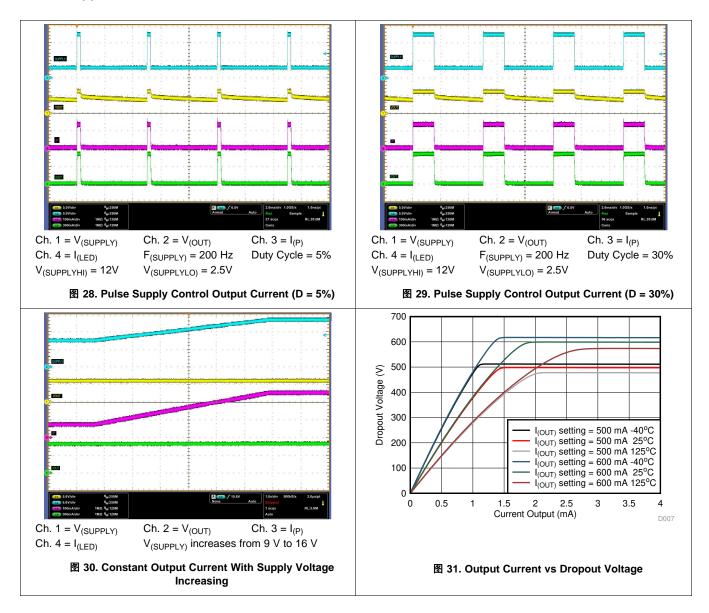


图 27. PWM Control With Heat Sharing Resistor

For PWM control scenarios, a NPN bipolar transistor with a base current-limiting resistor, R_5 can modulate the output current together with the device PWM function as 27. The resistor value of R_5 needs to be calculated based on the applied PWM voltage and β value of selected NPN transistor.



8.2.2.3 Application Curves





9 Power Supply Recommendations

The TPS92613-Q1 is designed to operate from an automobile electrical power system within the range specified in the *Recommended Operating Conditions*. The $V_{(SUPPLY)}$ input must be protected from reverse voltage and voltage dump condition over 40 V. The impedance of the input supply rail must be low enough that the input current transient does not cause drop below LED string required forward voltage. If the input supply is connected with long wires, additional bulk capacitance may be required in addition to normal input capacitor.

10 Layout

10.1 Layout Guidelines

Thermal dissipation is the primary consideration for TPS92613-Q1 layout. TI recommends large thermal dissipation area connected to thermal pads with multiple thermal vias.

10.2 Layout Example

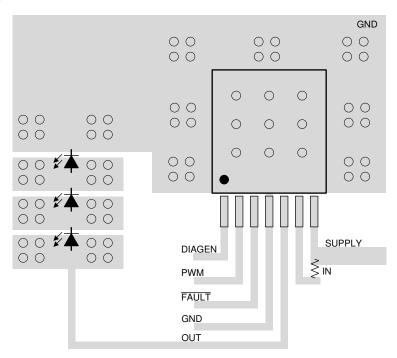


图 32. TPS92613-Q1 Example Layout Diagram



11 器件和文档支持

11.1 文档支持

11.1.1 相关文档

请参阅如下相关文档:

- 《TPS92610-Q1 汽车单通道线性 LED 驱动器》
- 《TPS92611-Q1 汽车单通道线性 LED 驱动器》
- 《TPS92612-Q1 汽车单通道线性 LED 驱动器》
- 《TPS92610-Q1 EVM 用户指南》
- 《如何在汽车外部照明应用中计算 TPS92630-Q1 最大输出 电流》
- 《适用于中央高位刹车灯 (CHMSL) 的汽车线性 LED 驱动器参考设计》
- 《适用于中央高位刹车灯 (CHMSL) 的汽车线性 LED 驱动器参考设计指南》

11.2 接收文档更新通知

要接收文档更新通知,请导航至 ti.com.cn 上的器件产品文件夹。单击右上角的通知我进行注册,即可每周接收产 品信息更改摘要。有关更改的详细信息,请查看任何已修订文档中包含的修订历史记录。

11.3 支持资源

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▲ SSD 的损坏小至导致微小的性能降级,大至整个器件故障。 精密的集成电路可能更容易受到损坏,这是因为非常细微的参数更改都可 能会导致器件与其发布的规格不相符。

11.6 Glossary

SLYZ022 — TI Glossary.

This glossary lists and explains terms, acronyms, and definitions.

12 机械、封装和可订购信息

以下页面包含机械、封装和可订购信息。这些信息是适用于指定器件的最新数据。数据如有变更,恕不另行通知, 且不会对此文档进行修订。如需获取此数据表的浏览器版本,请查看左侧的导航面板。



PACKAGE OPTION ADDENDUM

10-Dec-2020

PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
							(6)				
TPS92613QNDRRQ1	ACTIVE	TO-263	NDR	7	1000	RoHS & Green	SN	Level-3-260C-168 HR	-40 to 125	TPS92613Q	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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PACKAGE MATERIALS INFORMATION

www.ti.com 9-Aug-2022

TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device		Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TPS92613QNDRRQ1	TO-263	NDR	7	1000	330.0	24.4	10.6	15.4	2.45	12.0	24.0	Q2

PACKAGE MATERIALS INFORMATION

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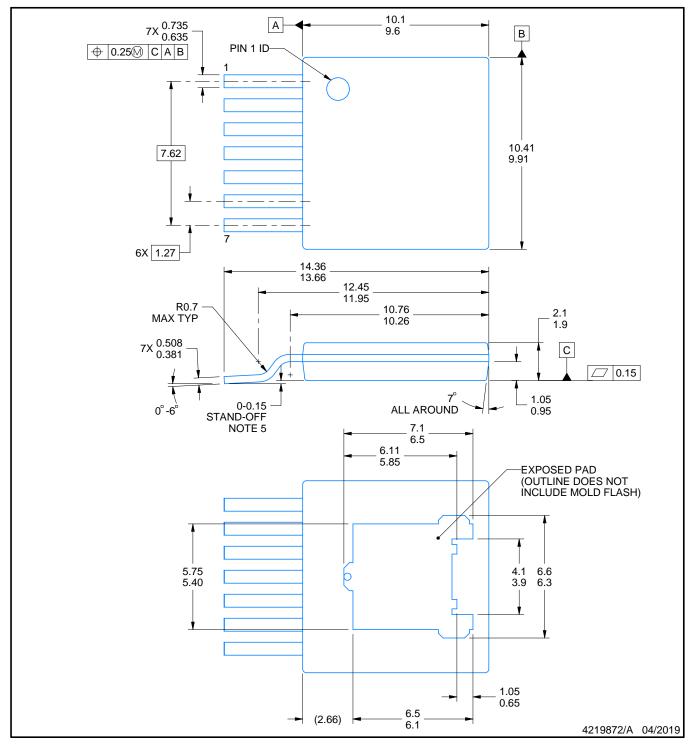


*All dimensions are nominal

	Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)	
I	TPS92613QNDRRQ1	TO-263	NDR	7	1000	367.0	367.0	45.0	



TO-263



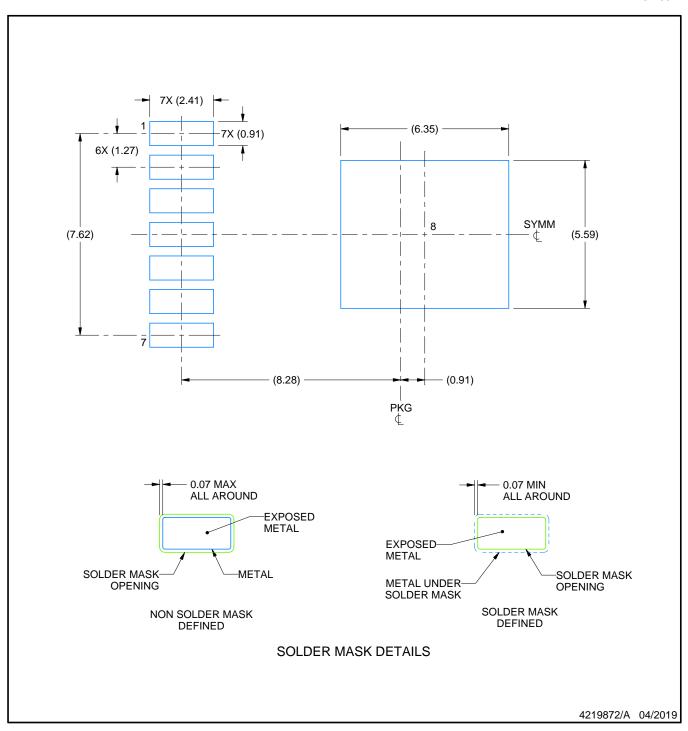
NOTES:

- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

 2. This drawing is subject to change without notice.
- Features may not exist and shape may vary per different assembly sites.
 Reference JEDEC registration TO-279B.
- 5. Under all conditions, leads must not be above Datum C



TO-263



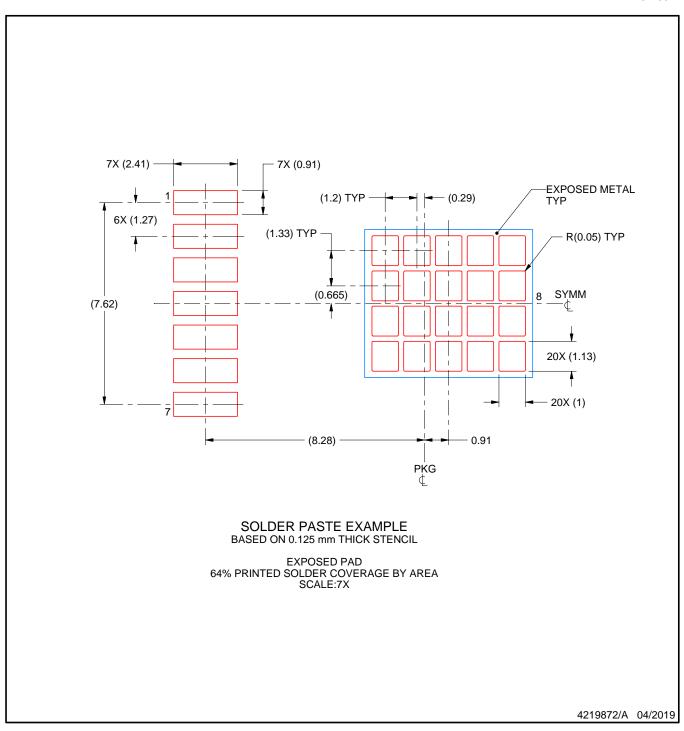
NOTES: (continued)



^{6.} This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature numbers SLMA002(www.ti.com/lit/slm002) and SLMA004 (www.ti.com/lit/slma004).

^{7.} Vias are optional depending on application, refer to device data sheet. It is recommended that vias under paste be filled, plugged or tented.

TO-263



NOTES: (continued)



^{8.} Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

9. Board assembly site may have different recommendations for stencil design.

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